

Title (en)  
Semiconductor manufacturing apparatus and method of manufacturing semiconductor device

Title (de)  
Vorrichtung zur Herstellung von Halbleitern und Verfahren zur Herstellung von Halbleitereinrichtungen

Title (fr)  
Appareil et méthode pour la fabrication d'un dispositif semi-conducteur

Publication  
**EP 1463094 A3 20061102 (EN)**

Application  
**EP 04007409 A 20040326**

Priority  
JP 2003085376 A 20030326

Abstract (en)  
[origin: EP1463094A2] A semiconductor manufacturing apparatus includes: a peeling mechanism to peel a pressure sensitive adhesive (PSA) tape from a semiconductor wafer constituted by a plurality of semiconductor chips which are separated therefrom, the semiconductor wafer having an element formation surface to form an element thereon and a rear surface opposite to the element formation surface, the PSA tape adhering to the element formation surface of the semiconductor wafer, each of the semiconductor chips having an adhesive layer formed on the rear surface; wherein the peeling mechanism has a sucking section which have a porous member to hold the semiconductor wafer by suction, the porous member being segmented into at least two sucking areas in the direction in which the PSA tape is peeled.

IPC 8 full level  
**H01L 21/00** (2006.01); **H01L 21/60** (2006.01); **H01L 21/68** (2006.01)

CPC (source: EP KR US)  
**B41J 29/10** (2013.01 - KR); **H01L 21/67132** (2013.01 - EP US); **H01L 21/6835** (2013.01 - EP US); **H01L 21/6836** (2013.01 - EP US); **H01L 21/6838** (2013.01 - EP US); **B41J 2/22** (2013.01 - KR); **H01L 2221/68327** (2013.01 - EP US); **H01L 2221/6839** (2013.01 - EP US); **Y10S 156/941** (2013.01 - EP US); **Y10S 438/976** (2013.01 - EP US); **Y10T 156/1052** (2015.01 - EP US); **Y10T 156/1179** (2015.01 - EP US); **Y10T 156/12** (2015.01 - EP US); **Y10T 156/19** (2015.01 - EP US)

Citation (search report)

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Designated contracting state (EPC)  
AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IT LI LU MC NL PL PT RO SE SI SK TR

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AL LT LV MK

DOCDB simple family (publication)  
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